

AMENDMENTS

In the Claims

The following is a marked-up version of the claims with the language that is underlined (“___”) being added and the language that contains strikethrough (“—”) being deleted:

1. (Currently Amended) An optoelectronic module, comprising:

a main body including material having high thermal conductivity for dissipating heat;

a flexible circuit, a majority of the flexible circuit conforming to an exterior of the main body;

a wafer-level package attached to the main body and electrically coupled to the flexible circuit, the wafer-level package including at least one optoelectronic device having an active region; and

an alignment element attached to the wafer-level package, the alignment element having features shaped to match with an optical fiber connector and align the active region of the optoelectronic device to an optical fiber.
2. (Original) A module as in claim 1, further comprising:

a fiber receptacle attached to the main body for coupling with an optical fiber connector.
3. (Original) A module as in claim 2. wherein the alignment element mates with a ferrule on the optical fiber connector.

4. (Original) A module as in claim 3, further comprising:
an auxiliary component attached to the main body, the auxiliary component coupled to the wafer-level package through the flexible circuit.
5. (Original) A module as in claim 4, further comprising a cover over the auxiliary component and attached to the main body.
6. (Original) A module as in claim 2, wherein the fiber receptacle is a mini MT-RJ connector.
7. (Original) A module as in claim 2, wherein the fiber receptacle is of a type selected from the group consisting of MPO, MT-RJ, FC, LC, SC₃ and ST connectors.
8. (Original) A module as in claim 1, the wafer-level package including:
a sub-mount having a first surface and a gasket formed on the first surface, wherein the optoelectronic device is attached to the first surface within the gasket; and
a lid attached to the sub-mount at the gasket, forming an enclosure containing the optoelectronic device.
9. (Original) A module as in claim 8, wherein the sub-mount comprises a first wafer and the lid comprises a second wafer.
10. (Original) A module as in claim 9, the wafer-level package further including:
a driver formed within the sub-mount for driving the optoelectronic device.

11. (Original) A module as in claim 9, the wafer-level package further including:
an amplifier formed within the sub-mount for amplifying a signal from the optoelectronic device.
12. (Original) A module as in claim 9, wherein the optoelectronic device is a light-emitting device.
13. (Original) A module as in claim 9, wherein the optoelectronic device is a light detector.
- 14 - 15 (Canceled)
16. (Original) A module as in claim 9, wherein the wafer-level package includes a light-emitting device and a light-detector.
17. (Original) A module as in claim 9, wherein the optoelectronic device has an active region, and
the lid of the wafer-level package includes an integrated lens aligned with the active region of the optoelectronic device
18. (Original) A module as in claim 9, further comprising a lens formed over the active region of the optoelectronic device.
19. (Original) A module as in claim 1, wherein the features of the alignment element are posts.

20. (Original) A module as in claim 19, wherein
the alignment element has a sloped surface to reduce back reflections.
21. (New) The module as in claim 1, wherein the exterior of the main body has a first face, an opposing second face, and a third face extending therebetween, and wherein the flexible circuit extends between the first face and the second face.
22. (New) The module as in claim 9, further including:
means for amplifying a signal from the optoelectronic device.